

IN THE CLAIMS

Please amend claim 12 as follows:

1 1. (Original) A method of manufacturing an electromagnetic wave shielding
2 filter, the method comprising:

3 preparing a metal plate for plating;

4 forming an insulating layer on an upper surface of the metal plate, the insulating
5 layer having a mesh pattern;

6 forming a plating layer on a remaining upper surface of the metal plate on which
7 the insulating layer is not formed;

8 arranging an adhesive film on the metal plate having the insulating layer and the
9 plating layer;

10 adhering the adhesive film to upper surfaces of the insulating layer and the plating
11 layer; and

12 separating the adhesive film from the metal plate so that the plating layer is
13 adhered to a lower surface of the adhesive film, the plating layer being in the form of a
14 mesh.

1 2. (Original) The method according to claim 1, wherein the metal plate
2 comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a
3 copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic

4 plating.

1 3. (Original) The method according to claim 1, wherein the insulating layer is
2 formed by oxide coating.

1 4. (Original) The method according to claim 1, wherein the plating layer
2 comprises at least one of copper or silver.

1 5. (Original) The method according to claim 1, wherein the adhesive film
2 comprises polyethylene terephthalate (PET).

1 6. (Original) The method according to claim 1, wherein the adhesive film
2 comprises a polymer film.

1 7. (Original) The method according to claim 1, wherein a binding force of the
2 plating layer to the adhesive film is stronger than a binding force of the plating layer to
3 the metal plate.

1 8. (Original) A method of manufacturing an electromagnetic wave shielding
2 filter, the method comprising:
3 preparing a metal plate for plating;

4 forming a photoresist layer on an upper surface of the metal plate, the photoresist
5 layer having a mesh pattern;

6 forming a plating layer on a remaining upper surface of the metal plate on which
7 the photoresist layer is not formed;

8 removing the photoresist layer from the metal plate;

9 arranging an adhesive film on the metal plate having the plating layer;

10 adhering the adhesive film to an upper surface of the plating layer; and

11 separating the adhesive film from the metal plate so that the plating layer is
12 adhered to a lower surface of the adhesive film, the plating layer being in the form of a
13 mesh.

1 9. (Original) The method according to claim 8, wherein the metal plate
2 comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a
3 copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic
4 plating.

1 10. (Original) The method according to claim 8, wherein the adhesive film
2 comprises a polymer film.

1 11. (Original) A method of manufacturing an electromagnetic wave shielding
2 filter, the method comprising:

3 preparing a substrate;
4 adhering a metal foil to an upper surface of the substrate;
5 forming a photoresist layer on an upper surface of the metal foil, the photoresist
6 layer having a mesh pattern;
7 forming a plating layer on a remaining upper surface of the metal foil on which the
8 photoresist layer is not formed;
9 removing the photoresist layer from the metal foil;
10 arranging an adhesive film on the metal foil having the plating layer;
11 adhering the adhesive film to an upper surface of the plating layer; and
12 separating the adhesive film from the metal foil so that the plating layer is adhered
13 to a lower surface of the adhesive film, the plating layer being in the form of a mesh.

1 12. (Currently Amended) The method according to claim 11, wherein the metal
2 [[plate]] foil comprises an alloy selected from at least one of SUS, a titanium alloy, a
3 nickel alloy, a copper alloy, and an iron alloy, the metal plate acting as a seed layer for
4 electrolytic plating.

1 13. (Original) The method according to claim 11, wherein the plating layer
2 comprises at least one of copper or silver.

1 14. (Original) The method according to claim 11, further comprising blackening

2 the surface of the plating layer to increase contrast, after forming the plating layer.

1 15. (Original) The method according to claim 11, wherein the adhesive film
2 comprises PET.

1 16. (Original) The method according to claim 11, wherein a binding force of the
2 plating layer to the adhesive film is stronger than a binding force of the plating layer to
3 the substrate or the metal foil.

1 17. (Original) The method according to claim 11, wherein the adhesive film
2 comprises a polymer film.

1 18. (Original) An electromagnetic wave shielding filter, manufactured by
2 preparing a substrate, forming a meshed plating layer on an upper surface of the substrate,
3 adhering an adhesive film to an upper surface of the plating layer, and separating the
4 adhesive film from the substrate so that the plating layer is adhered to a lower surface of
5 the adhesive film.

1 19. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the substrate is a metal plate arranged to act as a seed layer for electrolytic
3 plating.

1 20. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium
3 alloy, a nickel alloy, a copper alloy, or an iron alloy.

1 21. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the plating layer comprises at least one of copper or silver.

1 22. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the surface of the plating layer is blackened.

1 23. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the adhesive film comprises PET.

1 24. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein the adhesive film comprises a polymer film.

1 25. (Original) The electromagnetic wave shielding filter according to claim 18,
2 wherein a transparent layer containing an acrylic solid is further arranged on the upper
3 surface of the meshed plating layer to cover voids in the meshed plating layer.

1 26. (Original) The electromagnetic wave shielding filter according to claim 25,
2 wherein the transparent layer comprises at least one of an acrylate or a butyl carbitol.

1 27. (Original) The electromagnetic wave shielding filter according to claim 25,
2 wherein the transparent layer comprises 10% or less of an adhesive.